



PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Shinababu MIZUSAKI

Serial No. 09/847,370

GROUP 2827

Filed May 3, 2001

Examiner James M. Mitchell

ELECTRODE STRUCTURE OF A
CARRIER SUBSTRATE OF A SEMI-
CONDUCTOR DEVICE

SUPPLEMENTAL AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

Responsive to the Official Action of January 16, 2002
and supplemental to the amendment of April 16, 2002, please amend
the above-identified application as follows:

IN THE CLAIMS:

Add the following new claims:

--16. (new) An electrode structure of a carrier
substrate of a semiconductor device for solder-bonding the
semiconductor device to a main substrate, comprising:

a recess formed in a central area of the electrode
structure;

a circumferential wall surface surrounding said recess
of said central area; and

a through portion passing through said circumferential
wall surface and connecting between an inside portion of said
recess and an outer portion of said circumferential wall surface.